



SOT804-2

plastic thermal enhanced very thin quad flat package; no leads; 64 terminals; body 9 x 9 x 0.85 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN64
Package type industry code	HVQFN64
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
Mounting method type	S (surface mount)
Issue date	25-3-2004

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	8.95	-	9	9.05	mm
E	package width	8.95	-	9	9.05	mm
A	seated height	[tbd]	-	0.85	1	mm
A ₂	package height	[tbd]	-	0.85	[tbd]	mm
n ₂	actual quantity of termination	-	-	64	-	

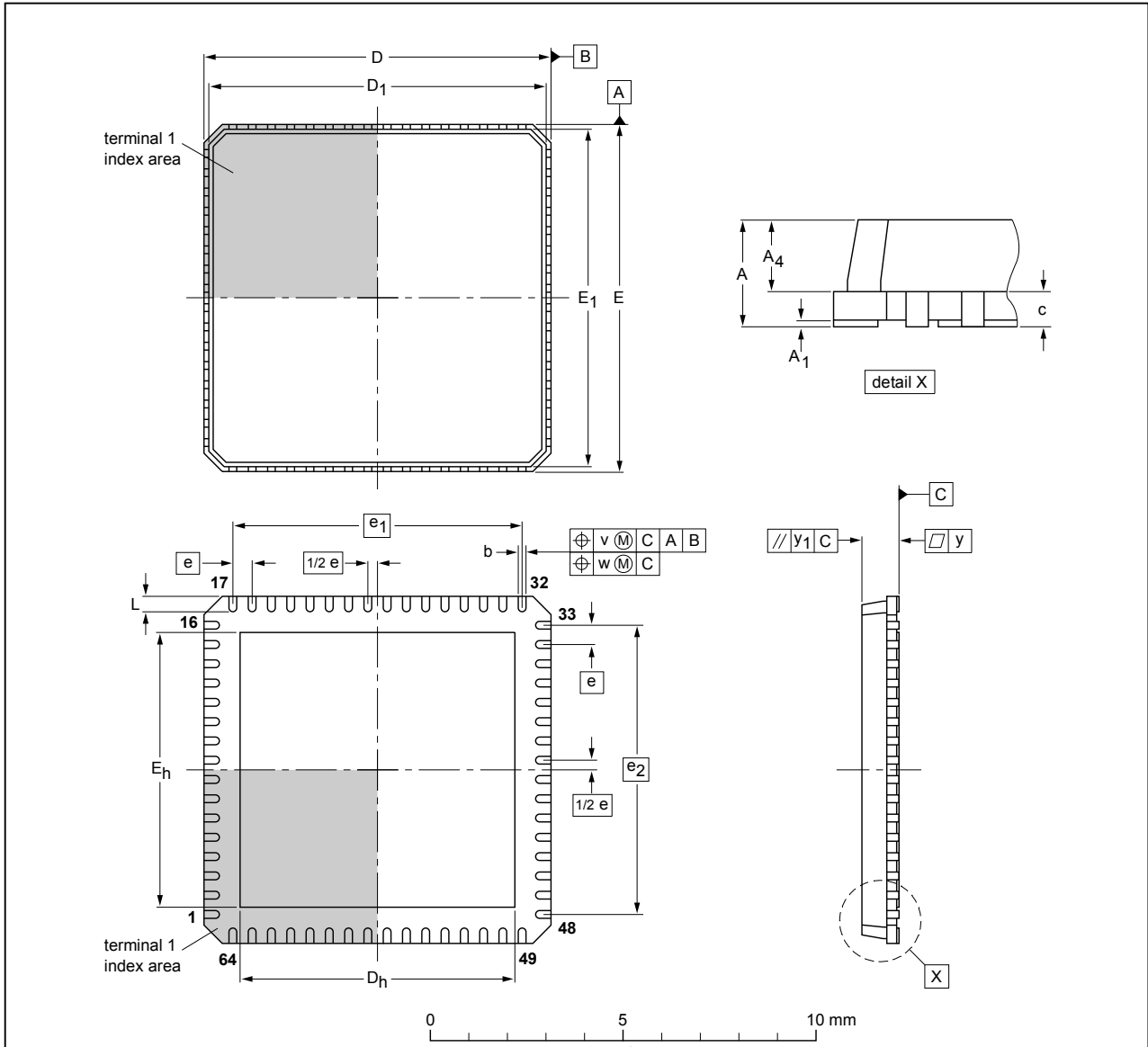


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2. Package outline

HVQFN64: plastic thermal enhanced very thin quad flat package; no leads; 64 terminals; body 9 x 9 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₄	b	c	D	D ₁	D _h	E	E ₁	E _h	e	e ₁	e ₂	L	v	w	y	y ₁
mm	1	0.05 0.00	0.80 0.65	0.30 0.18	0.2	9.05 8.95	8.95 8.55	7.25 6.95	9.05 8.95	8.95 8.55	7.25 6.95	0.5	7.5	7.5	0.5 0.3	0.1	0.05	0.05	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT804-2	---	MO-220	---			04-03-25

Fig. 1. Package outline HVQFN64 (SOT804-2)

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3. Soldering

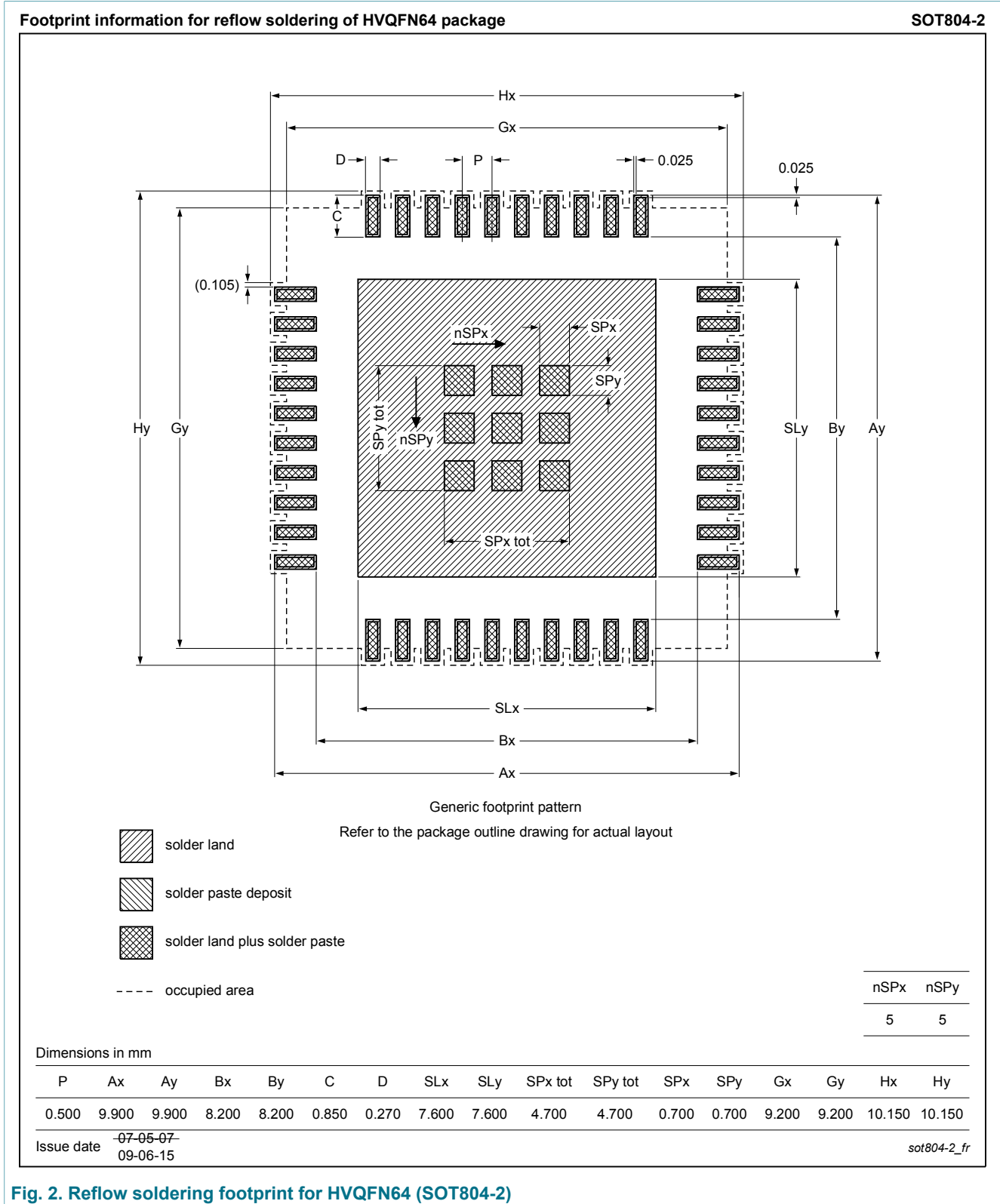


Fig. 2. Reflow soldering footprint for HVQFN64 (SOT804-2)

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4. Legal information

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5. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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